

PACKAGE STRUCTURE AND MANUFACTURING METHOD OF CHIP TYPE SEMICONDUCTOR

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Abstract

PROBLEM TO BE SOLVED: To improve the short circuit between electrodes in a package unit body and the decline in light emitting brightness as well as the peeling, disconnection of electrodes in the case of surface mounting in regard to the package structure of a chip type semiconductor.
SOLUTION: In a chip type semiconductor package structure 1 wherein respectively separate electrodes 11, 12 are conjugated with both ends (10a, 10b), on a P layer side and N layer side of a semiconductor chip 10 while the exposed surface of the semiconductor chip 10 is covered with a resin 15 on the other hand, the outside surface of the electrodes 11, 12 is at least partly exposed from the resin 15, the electrodes 11, 12 are composed to be conjugated so as to leave the not yet conjugated part with at least one end out of both ends 10a, 10b intact.

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